

IC Package Extraction Tool

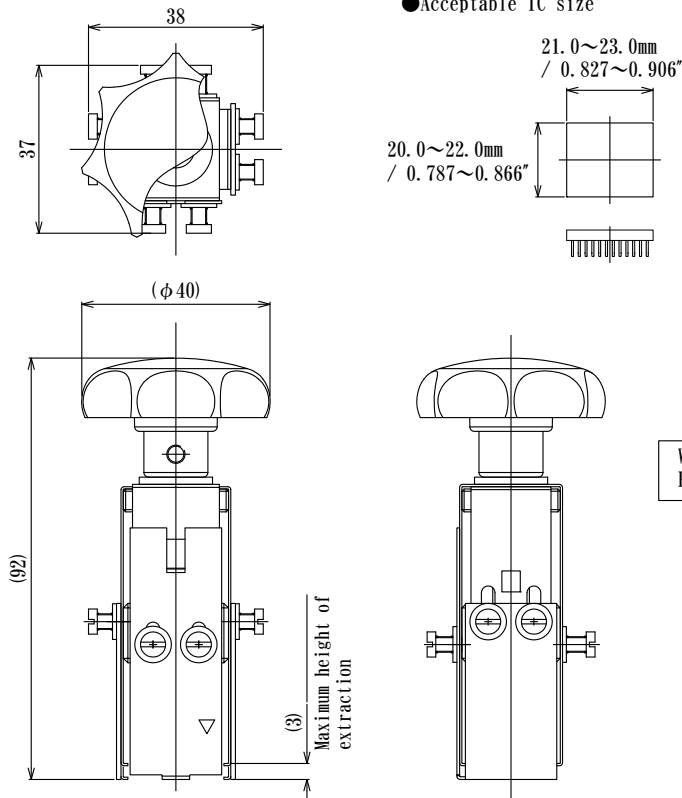
Features

- Easy extraction of IC package from IC socket.
- Vertical extraction prevents IC leads bending
- Suitable for need of high extraction force.

Extraction tool for PGA, SIP and DIP type IC package.

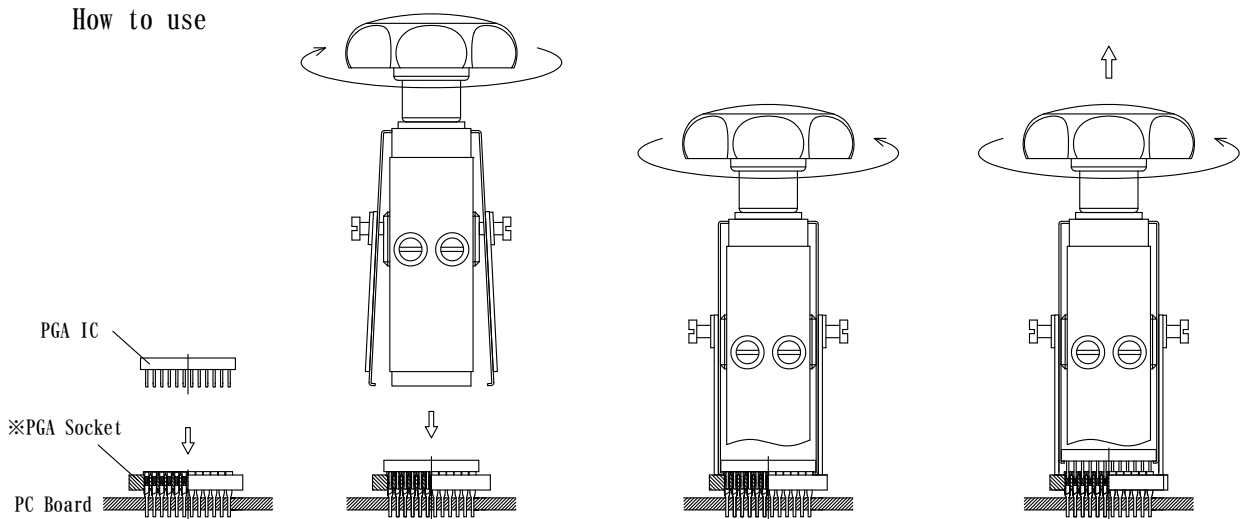
For PGA type IC Package.

PGA-NJG-TS4-3738-L92 (example)



We handle custom-made extraction tool.
Please feel free to contact us for more details.

How to use



※ Please refer to Page 3E1~3E2 for more information.

① Turn right the handle to open picker. Make sure the picker wide open. Set extraction tool over the IC.

② Turn left the handle to close picker and insert tip of picker between IC and IC socket.

③ Further turn left the handle. IC is extracted from IC socket. Then, pull up extraction tool.